Datasheet revision 1.1 www.HMTsolder.com

# Mildly Activated Rosin Flux, Type RMA

# **Product Applications**

HMT9-LF Flux consists of a homogeneous solution of water-white rosin in a multi-component solvent system with a brominated organic activator. It is completely chloride-free. The flux is widely used in electronic applications requiring excellent soldering activity and yielding residues with high water-extract resistivities

#### **Product Benefits**

High Solids Content
No-Clean
Alcohol-Based
Ideal for all rework, solder, and de-solder applications
Excellent wetting
Easily cleaned with isopropyl alcohol (IPA)
Can be used with Leaded and Lead-Free applications
RoHS 3 and REACH compliant

## **Specifications and Test Results**

Test J-STD-004 or other	Test Requirement	Result
requirement (as stated)		
Flux Classification	IPC-TM-650	ROL0
Copper Mirror	IPC-TM-650: 2.3.32	L: No Breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No Corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.05%
Electrochemical Migration	IPC-TM-650: 2.6.3.7	L: <1 decade drop (not cleaned)
Surface Insulation Resistance	IPC-TM-650: 2.6.3.7	L: ≥ 100 MΩ (No Clean)
40°C, 90% RH @ 168 Hours		
Free/Thaw Test		Pass
Visual	IPC-TM-650: 3.4.2.5	Clear and Free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No	Contains no substance >0.1% w/w
	1907/2006	that is listed as SVHC or restricted
		for use in solder materials.
Specific Gravity	N/A	0.90 ± 0.01
Density	N/A	7.5 lb/gal
Solids Content	N/A	45.5% ± 0.1
Flash Point TCC	N/A	12°C/180.1°F

#### **Product Use Guidelines**

## **Wave Soldering**

HMT9-LF Flux can be applied by foaming, brushing, dipping, rolling and spraying. Soldering need not be carried out immediately after fluxing. The residues are completely non-corrosive, non-conductive and fungus-proof, and need not be removed. However, cleaning is easily accomplished by vapor-degreasing methods, using appropriate solvent systems. The specific gravity of the flux increases with prolonged use as the solvents evaporate. It can be restored to the recommended value by adding Isopropyl Alcohol (IPA) as Flux Thinner to the flux and mixing thoroughly.

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# Storage and Shelf Life

Product should be stored in original sealed containers below 50°C. Shelf life under stated conditions is (2) years.

# **Packaging**

Container Sizes	1-gallon container, 5-gallon pail, 55-gallon drum, Flux Pens

# **Health and Safety**

HMT7-LF is a flammable product and should be handled with care and the normal precautions taken when working with chemical products. Recommended handling procedures are provided in the SDS.

Please refer to the Safety Data Sheet (SDS) before use. Safety data sheets can be found at www.hmtsolder.com

This data is based on information that the manufacturer believes to be reliable and offered in good faith. In no event will HMT be responsible for special, incidental and consequential damages. The user is responsible to the Administrative Authorities (regulations for the protection of the Environment) for the conformity of his installation.

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